

CLAIMS

What is Claimed is:

5 1. A thermosetting adhesive sheet with electroconductive and thermoconductive properties, comprising:

a) a thermosetting adhesive sheet having two major surfaces, composed of a thermosetting adhesive composition comprising an ethylene-glycidyl (meth)acrylate copolymer and a rosin, said rosin containing a carboxyl group, where crosslinking is
10 formed between the ethylene of said copolymer by electron beam radiation, and having at least one through-opening region formed at a prescribed location, and

b) low melting point solder placed within said at least one through-opening region formed at the prescribed location, to provide electrical and thermal
conductivity at the prescribed location(s).

15 2. A thermosetting adhesive sheet according to claim 1, wherein said thermosetting adhesive composition further comprises an ethylene-alkyl (meth)acrylate copolymer.

20 3. A thermosetting adhesive sheet according to claim 1, wherein said thermosetting adhesive sheet further comprises a release sheet on at least one surface thereof.

25 4. An electronic structure comprising a thermosetting adhesive sheet according to claim 1, wherein said thermosetting adhesive sheet is a heat-radiating adhesive sheet which is positioned between an electronic element and a heat radiating means and adheres said electronic element to said heat radiating means.

5. An electronic structure according to claim 4, wherein said prescribed location of said through-opening region touches said electronic element.